

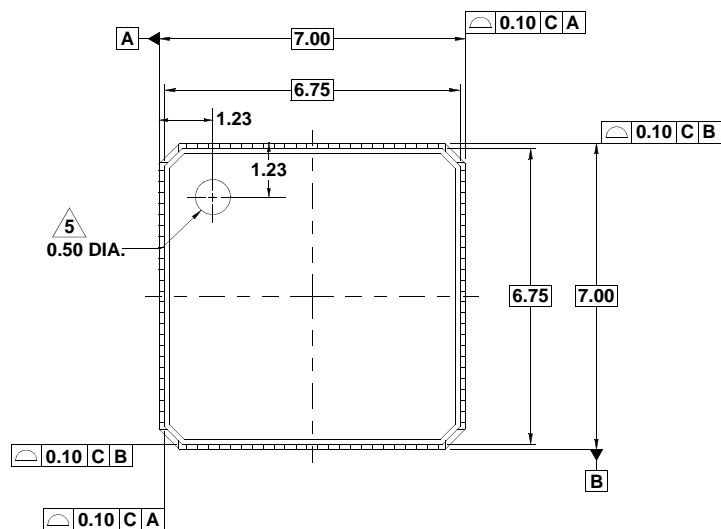
Plastic Packages for Integrated Circuits

Package Outline Drawing

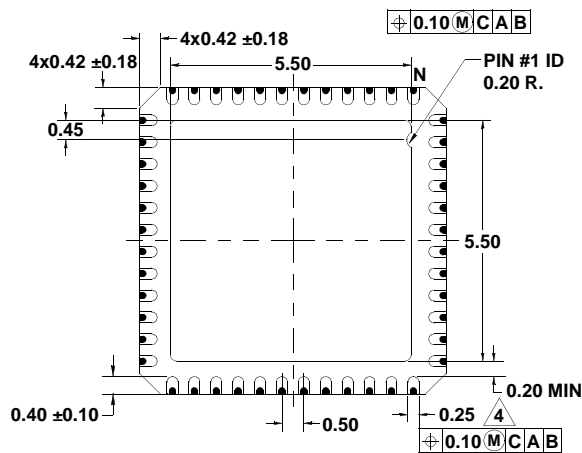
L48.7x7X

48 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (PUNCH QFN)

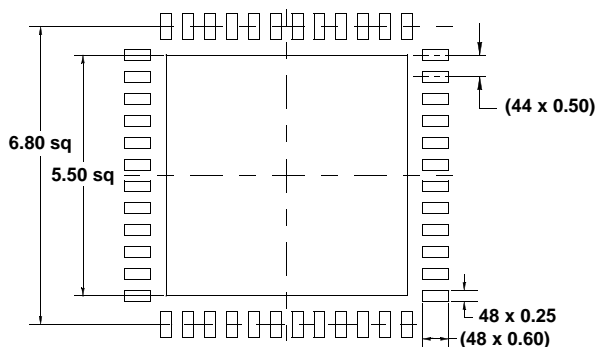
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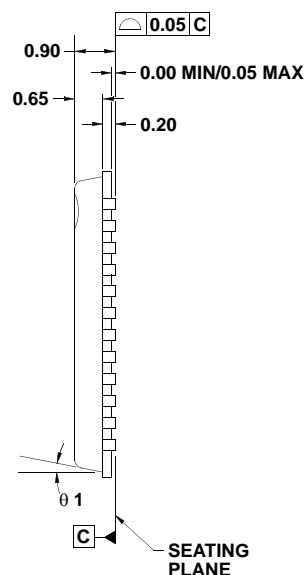
TOP VIEW



BOTTOM VIEW



TYPICAL RECOMMENDED LAND PATTERN



SIDE VIEW

NOTES:

1. Dimensions are in millimeters.
2. Die thickness allowable is 0.305mm maximum (0.012 inches maximum).
3. Dimensioning & tolerances conform to ASME Y14.5m. - 1994.
4. Dimension applies to plated terminal and is measured between 0.20mm and 0.25mm from terminal tip.
5. The pin #1 identifier must be placed on the top surface of the package by using indentation mark or other feature of package body.
6. Exact shape and size of this feature is optional.
7. Package warpage max 0.08mm.
8. Applied for exposed pad and terminals. Exclude embedding part of exposed pad from measuring.
9. Applied only to terminals.
10. Package corners, unless otherwise specified, are R0.175 ±0.025mm.